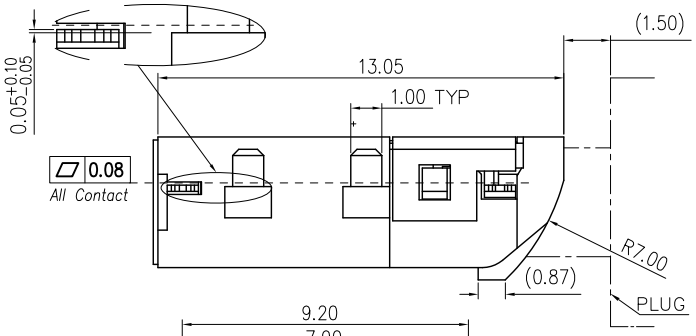
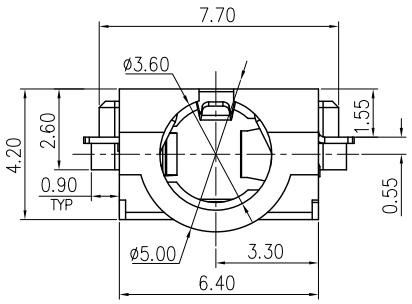
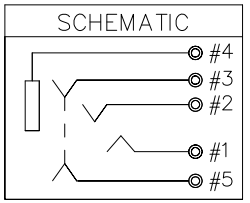
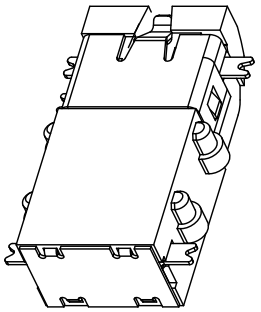
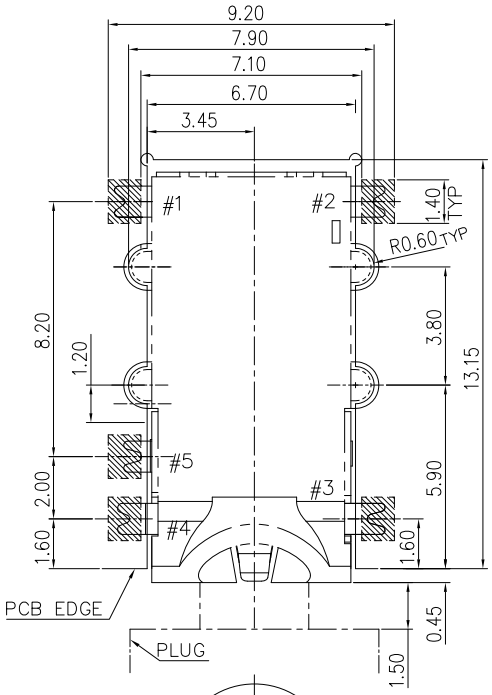
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCTS RELEASE	Kim	07/10'10
B	ECN:C110387 Modify plating	LONGJIANG	2011.12.09
C	ECN:C130269 UPDATE DRAWING	TFY	2014.4.21

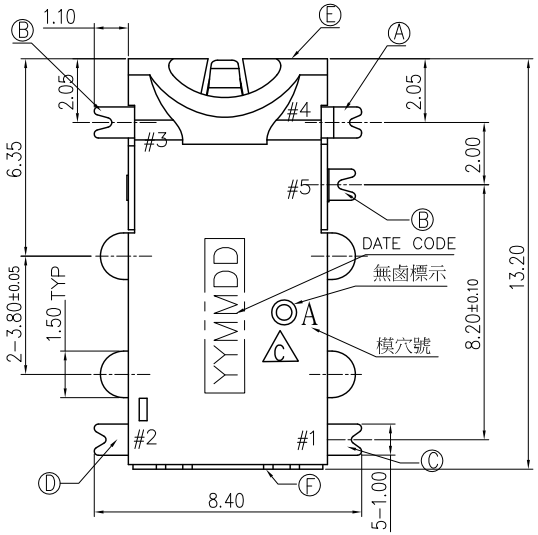






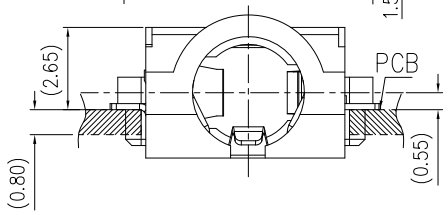




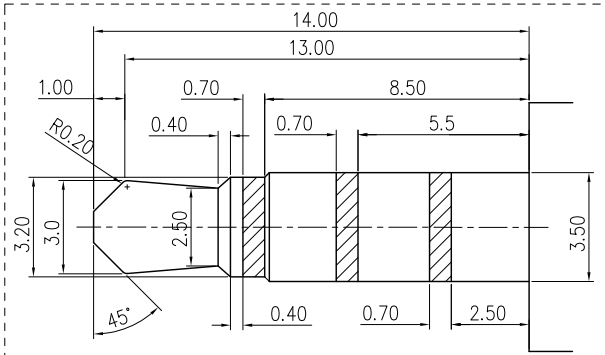


SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:
   1-1.RATING: 12V MAX.
   1-2.CONTACT RESISTANCE: 30mΩ MAX(INITIAL).
2. MECHANICAL CHARACTERISTICS:
   2-1. INSERTION FORCE : 3.0KGF MAX
   2-2. WITHDRAWAL FORCE : 0.3KGF MIN
3. LIFE TEST: 10,000 CYCLES MIN.
4. PACKAGING: TAPE & REEL
5. TO CONFORM TO THE SINGATRON HSF SPECIFICATION.
6. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ⊙
7. HALOGEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: HF
8. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
9. SOLDER HEAT RESISTANCE REFLOW SOLDERING 260°C 10SECS.
10. DATE CODE: YY MM DD
    - YY: Year
    - MM: Month
    - DD: Day



RECOMMENDED PCB LAYOUT
TOP VIEW (TOLERANCE:±0.05)



3.5ø 4POLE PLUG (TOLERANCE:±0.05)

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
F	COVER	1	SUS	
E	BODY	1	HI-TEMP THERMOPLASTIC UL94V-0	BLACK COLOR
D	RING SPRING A	1	COPPER ALLOY 0.2t	GOLD FLASH
C	TIP SPRING	1	COPPER ALLOY 0.2t	Gold flash on contact area And solder tail,all over Nickel plated Ⓑ
B	RING SPRING B	2	COPPER ALLOY 0.2t	GOLD FLASH
A	EARTH	1	COPPER ALLOY 0.2t	GOLD FLASH

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.5, X.X :±0.3, X.XX :±0.2
ANGLES: X :±2°, X.X :±1°

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5ø PHONE JACK		
DWN	TFY 14/4/29	PART NO. 2SJ2317-000111	
CHKD	ZJZ 14/4/29	SCALE 6:1	UNIT: mm
APVD	Liao 14/4/29	SIZE: A3	SHEET: 1OF1 REV: C

CUSTOMER COPY

文件編號 RD-06-043-A